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## BIB DATA SHEET

CONFIRMATION NO. 5291

<b>SERIAL NUMBER</b> 10/828,492	<b>FILING or 371(c) DATE</b> 04/21/2004 <b>RULE</b>	<b>CLASS</b> 327	<b>GROUP ART UNIT</b> 2826	<b>ATTORNEY DOCKET NO.</b> 60188-820		
<b>APPLICANTS</b> Sadami Takeoka, Osaka, JAPAN; Mitsuyasu Ohta, Osaka, JAPAN; Osamu Ichikawa, Osaka, JAPAN; Masayoshi Yoshimura, Kyoto, JAPAN;						
<b>** CONTINUING DATA *****</b> This application is a DIV of 10/187,269 07/02/2002 PAT 6,734,549						
<b>** FOREIGN APPLICATIONS *****</b> JAPAN 2001-201950 07/03/2001						
<b>** IF REQUIRED, FOREIGN FILING LICENSE GRANTED **</b> 06/29/2004						
Foreign Priority claimed <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No 35 USC 119(a-d) conditions met <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Verified and Acknowledged <u>/THOMAS L DICKEY/</u> Examiner's Signature		<input type="checkbox"/> Met after Allowance TD Initials	<b>STATE OR COUNTRY</b> JAPAN	<b>SHEETS DRAWINGS</b> 25	<b>TOTAL CLAIMS</b> 8	<b>INDEPENDENT CLAIMS</b> 4
<b>ADDRESS</b> McDermott, Will & Emery 600 13th Street, N.W. Washington, DC 20005-3096 UNITED STATES						
<b>TITLE</b> Semiconductor wiring substrate, semiconductor device, method for testing semiconductor device, and method for mounting semiconductor device						
<b>FILING FEE RECEIVED</b> 856	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit			